

## Patent Abstracts of Japan

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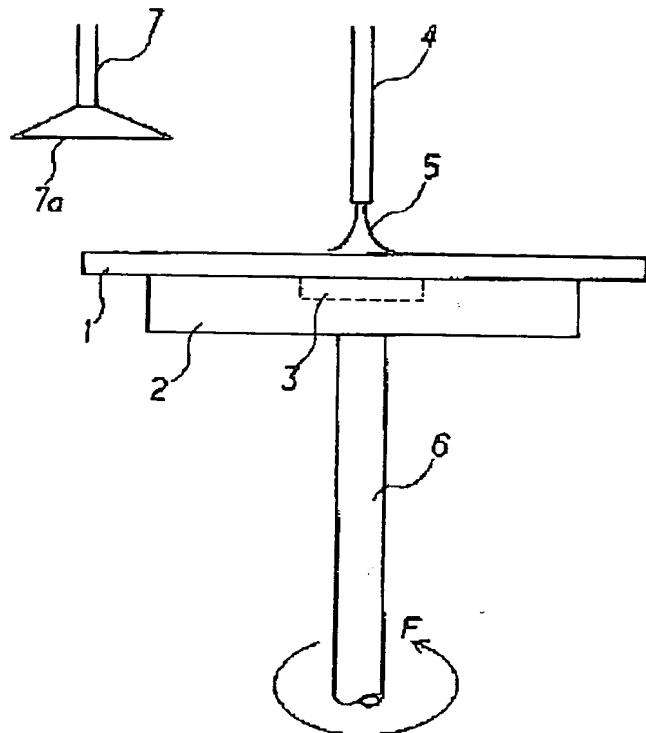
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TITLE : SPIN COATING ON SEMICONDUCTOR  
 SUBSTRATE AND DEVICE



**ABSTRACT :** PURPOSE: To form a coating layer having no dead spot regardless of the presence or absence of a defect in the surface of a semiconductor substrate by a method wherein before a coating solution is dripped, a solvent is sprayed on the whole surface of the semiconductor substrate in a spray form.

**CONSTITUTION:** A solvent spray nozzle 7 is moved to the central part of a substrate 1 to position and a solvent is sprayed on the whole surface of the substrate 1 in a spray form through a funnel-shaped blow-off port 7. Then, after the nozzle 7 is moved aside to the side part of the substrate, a coating nozzle 4 is positioned to the central part of the substrate 1 and a coating solution 5 is dripped on the central part in a prescribed amount. After that, a rotating stage 2 is rotated in the direction indicated by arrow F at high speed via a spindle shaft 6 and the solution 5 is spread on the whole surface of the substrate 1. Thereby, regardless of the presence or absence of a defect in the surface of the substrate 1 a coating layer having no dead spot can be obtained and the quality and yield of the substrate can be improved.

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